

United States Patent and Trademark Office

UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, Virginia 22313-1450 www.uspto.gov

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/685,569	10/16/2003	Beom-Jun Jin	SEC.872D	7173
75	90 07/13/2004		EXAMI	NER
VOLENTINE FRANCOS, P.L.L.C.			WILSON, SCOTT R	
Suite 150 12200 Sunrise Valley Drive			ART UNIT	PAPER NUMBER
Reston, VA 20191			2826	
			DATE MAILED: 07/13/2004	

Please find below and/or attached an Office communication concerning this application or proceeding.

		Application No.	Applicant(s)				
Office Action Summary		10/685,569	JIN ET AL.				
		Examiner	Art Unit				
		Scott R. Wilson	2826				
The MAILING DATE of this communication appears on the cover sheet with the correspondence address Period for Reply							
THE N - Extense after S - If the s - If NO - Failum Any re	DRTENED STATUTORY PERIOD FOR REPL MAILING DATE OF THIS COMMUNICATION. sions of time may be available under the provisions of 37 CFR 1.1 SIX (6) MONTHS from the mailing date of this communication. period for reply specified above is less than thirty (30) days, a repl period for reply is specified above, the maximum statutory period to to reply within the set or extended period for reply will, by statute eply received by the Office later than three months after the mailine d patent term adjustment. See 37 CFR 1.704(b).	136(a). In no event, however, may a reply be timely within the statutory minimum of thirty (30) days will apply and will expire SIX (6) MONTHS from a cause the application to become ABANDONE	nely filed s will be considered timely. the mailing date of this communication. D (35 U.S.C. § 133).				
Status							
1)🖂	1)⊠ Responsive to communication(s) filed on <u>16 October 2003</u> .						
2a) <u></u> ☐	This action is FINAL . 2b)⊠ This action is non-final.						
•—	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.						
Disposition	on of Claims						
•	4) Claim(s) <u>1-20</u> is/are pending in the application.						
	4a) Of the above claim(s) is/are withdrawn from consideration. 5) Claim(s) is/are allowed.						
· <u> </u>	☐ Claim(s) is/are allowed. ☐ Claim(s) <u>1,2,5,6,8-11 and 13-20</u> is/are rejected.						
·	Claim(s) <u>3,4,7 and 12</u> is/are objected to.						
•							
Application	on Papers						
9) The specification is objected to by the Examiner.							
10)⊠ The drawing(s) filed on 16 October 2003 is/are: a)⊠ accepted or b)□ objected to by the Examiner.							
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).							
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d). 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.							
Priority u	nder 35 U.S.C. § 119	,					
•	Acknowledgment is made of a claim for foreign ☑ All b)☐ Some * c)☐ None of:	n priority under 35 U.S.C. § 119(a)	-(d) or (f).				
•	1. ☐ Certified copies of the priority document	ts have been received.					
	2.☐ Certified copies of the priority document		on No				
	 Copies of the certified copies of the prio application from the International Burea 		ed in this National Stage				
* S	ee the attached detailed Office action for a list		d.				
Attachment	(s)						
	e of References Cited (PTO-892)	4) Interview Summary					
3) N Inform	e of Draftsperson's Patent Drawing Review (PTO-948) nation Disclosure Statement(s) (PTO-1449 or PTO/SB/08) No(s)/Mail Date <u>10/16/03</u> .	Paper No(s)/Mail Da 5) Notice of Informal P 6) Other:	atent Application (PTO-152)				

DETAILED ACTION

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 1, 2, 5, 6 and 8 are rejected under 35 U.S.C. 102(b) as being anticipated by Graettinger et al.. Graettinger et al., Figure 14, discloses a semiconductor memory device having a storage node contact hole (850) aligned at bit line spacers (Figure 2, element 130) formed at both side walls of a bit line stack (120) and exposing a pad (1100), the device comprising a multi-layered storage node contact plug (col. 5, line 64) formed in the storage node contact hole (850), the multi-layered storage node contact plug having a first storage node contact plug (1200) and a second storage node contact plug (610) formed on the first storage node contact plug.

As to claim 2, Graettinger et al. discloses (col. 7, lines 40-44) that the first storage node contact plug (1200) is formed of titanium nitride and the second storage node contact plug (610) is formed from polysilicon (col. 5, lines 32-33).

As to claim 5, Graettinger et al., Figure 14, discloses (col. 5, lines 54-55) a barrier metal layer (800) formed on the second storage node contact plug, wherein the barrier metal layer functions as a third storage node contact plug (col. 5, line 64).

As to claim 6, Graettinger et al. discloses (col. 5, line 55) that the barrier metal layer is formed from titanium nitride.

As to claim 8, Graettinger et al., Figure 14, discloses that the second storage node contact plug (610) is thicker than the first storage node contact plug (1200).

Claims 9-11 and 13 are rejected under 35 U.S.C. 102(b) as being anticipated by Graettinger et al.. Graettinger et al., Figure 14, discloses a semiconductor memory device comprising a pad (1100)

Application/Control Number: 10/685,569

Art Unit: 2826

formed on a semiconductor substrate, an interlayer dielectric layer (150) formed on the pad and substrate to insulate the pad, a bit line stack (120) formed on the interlayer dielectric layer, a pair of bit line spacers (130) formed at both side walls of the bit line stack, a storage node contact hole (850) formed within the interlayer dielectric layer, exposing the pad and aligned between the bit line spacers, and a multi-layered storage node contact plug formed within the storage node contact hole, including a first storage node contact plug (1200) and a second storage node contact plug (610) formed on the first storage node contact plug.

As to claim 10, Graettinger et al. discloses (col. 7, lines 40-44) that the first storage node contact plug (1200) is formed of titanium nitride and the second storage node contact plug (610) is formed from polysilicon (col. 5, lines 32-33).

As to claim 11, Graettinger et al. (col. 4, lines 1-4) discloses the bit line stack to be comprised of a bit line barrier metal layer (124), a bit line conductive layer (122) and a bit line cap layer (140), which are sequentially deposited.

As to claim 13, Graettinger et al., Figure 14, discloses a barrier metal layer (800) formed on the second storage node contact plug.

As to claims 14-20, the device of Graettinger et al. would necessarily have to be formed in order to function, so that the method comprising the means of forming the device is inherent in the device structure itself.

Allowable Subject Matter

Claims 3 and 4 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims. No prior art discloses the claimed multi-layer contact plug with an ohmic contact layer formed under the first contact plug.

Claim 7 is objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

No prior art discloses the claimed multi-layer contact plug formed over a polysilicon pad.

Application/Control Number: 10/685,569

Art Unit: 2826

Claim 12 is objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

No prior art discloses the claimed memory device with a bit line stack formed with a titanium nitride barrier metal layer, a conductive tungsten layer and a silicon nitride cap layer.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Scott R. Wilson whose telephone number is 571-272-1925. The examiner can normally be reached on M-F 8:30 - 4:30 Eastern.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor,

Nathan Flynn can be reached on 571-272-1915. The fax phone number for the organization where this

application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

srw

MATHAN J. FLYNN SUPERVISORY PATENT EXAMINER TECHNOLOGY CENTER 2800

srw July 9, 2004